



**RF360**  
**Europe GmbH**

## **Data sheet**

### **SAW Tx post PA filter**

Small cell & femtocell

TD-LTE band 40partial (2320-2370MHz)

Series/type:	B9637
Ordering code:	B39232B9637P810
Date:	January 18, 2019
Version:	2.1

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RF360 Europe GmbH  
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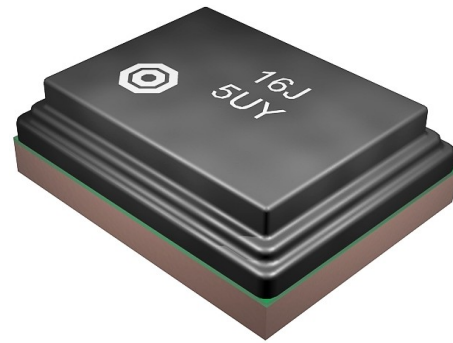
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## 1 Application

- Low-loss RF filter for smallcells
- Usable pass band 50 MHz

## 2 Features

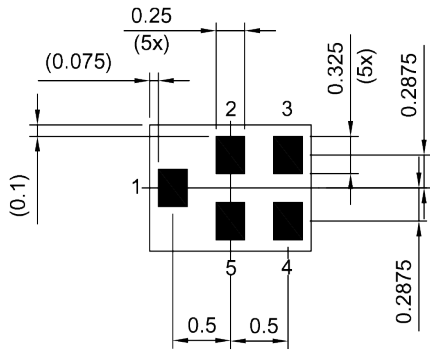
- Industrial grade qualified family
- Package size  $1.4_{\pm 0.1}$  mm  $\times$   $1.1_{\pm 0.1}$  mm
- Package height 0.45 mm (max.)
- Approximate weight 3 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 2a (MSL2a)



**Figure 1:** Picture of component with example of product marking.

3 Package

BOTTOM VIEW

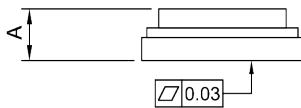


Pad and pitch tolerance ±0.05

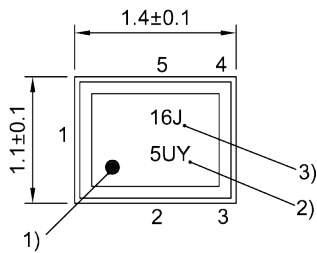
4 Pin configuration

- 1 Input
- 4 Output
- 2, 3, 5 Ground

SIDE VIEW

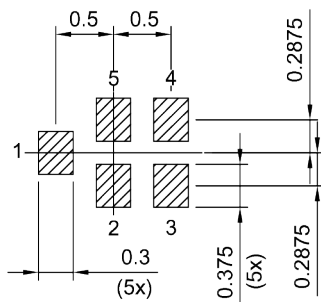


TOP VIEW



- 1) Marking for pad number 1
- 2) Example of encoded lot number
- 3) Example of encoded filter type number

Land pattern THRU VIEW



Landing pad tolerance -0.02

**Figure 2:** Drawing of package with package height A = 0.45 mm (max.). See Sec. Package information (p. 21).

5 Matching circuit

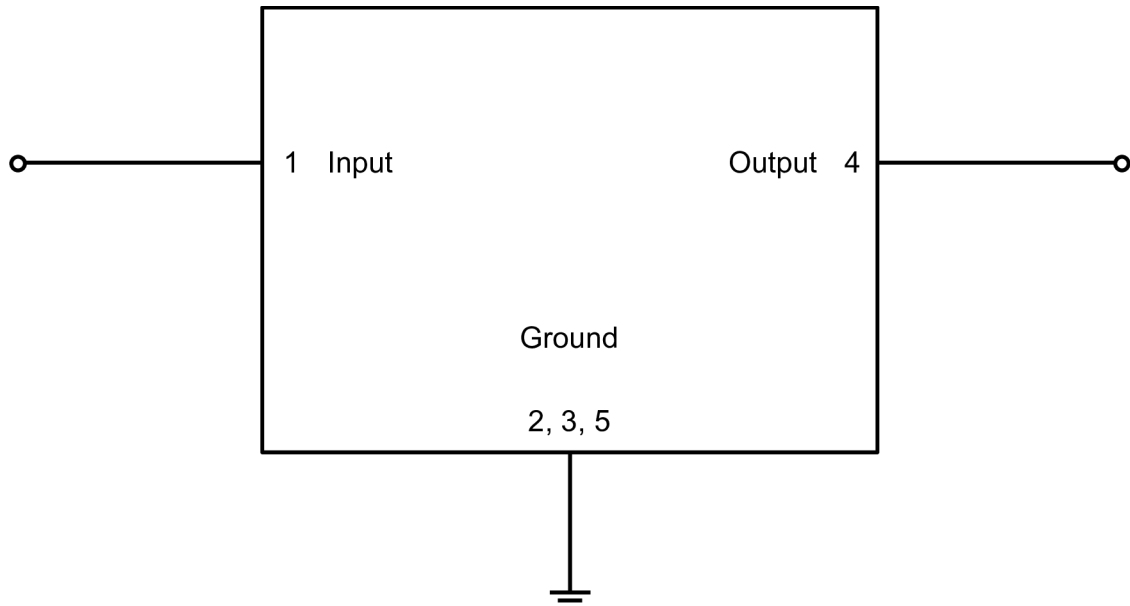


Figure 3: Schematic of matching circuit. No external matching components required.



## 6 Characteristics

Temperature range for specification	$T_{SPEC}$	= -10 °C ... +85 °C
Input terminating impedance	$Z_{IN}$	= 50 $\Omega$
Output terminating impedance	$Z_{OUT}$	= 50 $\Omega$

Characteristics			min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Center frequency</b>		$f_C$	—	2345	—	MHz
<b>Maximum insertion attenuation</b>	2320... 2370	MHz	$\alpha_{max}$	2.1	2.9	dB
<b>Amplitude ripple (p-p)</b>	2320... 2370	MHz	$\Delta\alpha$	1.2	2.0	dB
<b>Maximum VSWR</b>			VSWR <sub>max</sub>			
@ input port	2320... 2370	MHz		1.7	2.0	
@ output port	2320... 2370	MHz		1.7	2.0	
<b>Maximum error vector magnitude</b>	2322.4... 2367.6	MHz	EVM <sub>max</sub> <sup>1)</sup>	1.0	3.0	%
<b>Minimum attenuation</b>			$\alpha_{min}$			
	50... 1574	MHz		29	36	dB
	1574... 1577	MHz		29	37	dB
	1577... 1710	MHz		29	37	dB
	1710... 1805	MHz		30	39	dB
	1805... 1845	MHz		33	40	dB
	1845... 1880	MHz		33	40	dB
	1920... 2110	MHz		35	42	dB
	2110... 2170	MHz		33	45	dB
	2170... 2200	MHz		33	41	dB
	2200... 2215	MHz		33	39	dB
	2215... 2280	MHz		15	30	dB
	2280... 2295	MHz		15	26	dB
	2295... 2300	MHz		12	20	dB
	2395... 2400	MHz		10	41	dB
	2400... 2410	MHz		30	47	dB
	2410... 2420	MHz		40	55	dB
	2420... 2440	MHz		45	55	dB
	2440... 2460	MHz		45	54	dB
	2460... 2480	MHz		45	50	dB
	2480... 2490	MHz		43	48	dB
	2490... 2500	MHz		43	48	dB
	2500... 2570	MHz		40	45	dB
	2570... 2620	MHz		40	45	dB
	2620... 2690	MHz		40	45	dB
	2690... 3750	MHz		32	42	dB

Characteristics			min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
	3750... 4600	MHz	25	36	—	dB
	4600... 4800	MHz	25	35	—	dB
	4800... 5150	MHz	20	34	—	dB
	5150... 5850	MHz	20	32	—	dB
	5850... 6000	MHz	20	31	—	dB

<sup>1)</sup> Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

Temperature range for specification	$T_{SPEC}$	= -40 °C ... +95 °C
Input terminating impedance	$Z_{IN}$	= 50 $\Omega$
Output terminating impedance	$Z_{OUT}$	= 50 $\Omega$

Characteristics			min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
<b>Center frequency</b>		$f_C$	—	2345	—	MHz
<b>Maximum insertion attenuation</b>	2320... 2370	MHz	$\alpha_{max}$	2.1	4.0 <sup>1)</sup>	dB
<b>Amplitude ripple (p-p)</b>	2320... 2370	MHz	$\Delta\alpha$	1.2	3.1 <sup>2)</sup>	dB
<b>Maximum VSWR</b>			VSWR <sub>max</sub>			
@ input port	2320... 2370	MHz		1.7	2.3	
@ output port	2320... 2370	MHz		1.7	2.3	
<b>Maximum error vector magnitude</b>	2322.4... 2367.6	MHz	EVM <sub>max</sub> <sup>3)</sup>	1.0	4.5	%
<b>Minimum attenuation</b>			$\alpha_{min}$			
	50... 1574	MHz		29	36	dB
	1574... 1577	MHz		29	37	dB
	1577... 1710	MHz		29	37	dB
	1710... 1805	MHz		30	39	dB
	1805... 1845	MHz		33	40	dB
	1845... 1880	MHz		33	40	dB
	1920... 2110	MHz		35	42	dB
	2110... 2170	MHz		33	45	dB
	2170... 2200	MHz		33	41	dB
	2200... 2215	MHz		33	39	dB
	2215... 2280	MHz		15	30	dB
	2280... 2295	MHz		15	26	dB
	2295... 2300	MHz		10	20	dB
	2395... 2400	MHz		6	41	dB
	2400... 2410	MHz		20	47	dB
	2410... 2420	MHz		40	55	dB
	2420... 2440	MHz		45	55	dB
	2440... 2460	MHz		45	54	dB
	2460... 2480	MHz		45	50	dB
	2480... 2490	MHz		43	48	dB
	2490... 2500	MHz		43	48	dB
	2500... 2570	MHz		40	45	dB
	2570... 2620	MHz		40	45	dB
	2620... 2690	MHz		40	45	dB
	2690... 3750	MHz		32	42	dB
	3750... 4600	MHz		25	36	dB
	4600... 4800	MHz		25	35	dB

Characteristics			min. for $T_{SPEC}$	typ. @ +25 °C	max. for $T_{SPEC}$	
	4800... 5150	MHz	20	34	—	dB
	5150... 5850	MHz	20	32	—	dB
	5850... 6000	MHz	20	31	—	dB

- <sup>1)</sup> 3.3dB valid for Temperature= -10 °C ... +95 °C
- <sup>2)</sup> 2.4dB valid for Temperature= -10 °C ... +95 °C
- <sup>3)</sup> Error Vector Magnitude (EVM) based on definition in 3GPP TS 25.141.

## 7 Maximum ratings

Operable temperature	$T_{OP} = -40\text{ °C} \dots +95\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -40\text{ °C} \dots +95\text{ °C}$	
DC voltage	$ V_{DC} ^{2)} = 0\text{ V}$	
ESD voltage		
	$V_{ESD}^{3)} = 50\text{ V}$	Machine model.
	$V_{ESD}^{4)} = 225\text{ V}$	Human body model.
Input power	$P_{IN}$	
@ input port: 2320 ... 2370 MHz	26 dBm <sup>5)</sup>	TD-LTE 5 MHz LTE downlink signal (25 RB), ON-state power 70% DC for 100000 h @ 55 °C. Source and load impedance 50Ω.
@ input port: 2320 ... 2370 MHz	27 dBm <sup>5), 6)</sup>	TD-LTE 5 MHz LTE downlink signal (25 RB), ON-state power 70% DC for 30000 h @ 55 °C. Source and load impedance 50Ω.
@ Elsewhere	10 dBm	

<sup>1)</sup> Not valid for packaging material. Storage temperature for packaging material is -25 °C to +40 °C.

<sup>2)</sup> In case of applied DC voltage blocking capacitors are mandatory.

<sup>3)</sup> According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

<sup>4)</sup> According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

<sup>5)</sup> Expected lifetime according to accelerated power durability simulation and wear out models.

<sup>6)</sup>  $T_{SPEC}$  is the ambient temperature of the PCB at component position. Specified min./max values from section 6 "characteristics" for maximum input power 27dBm are valid for temperature up to 55°C.

8 Transmission coefficient

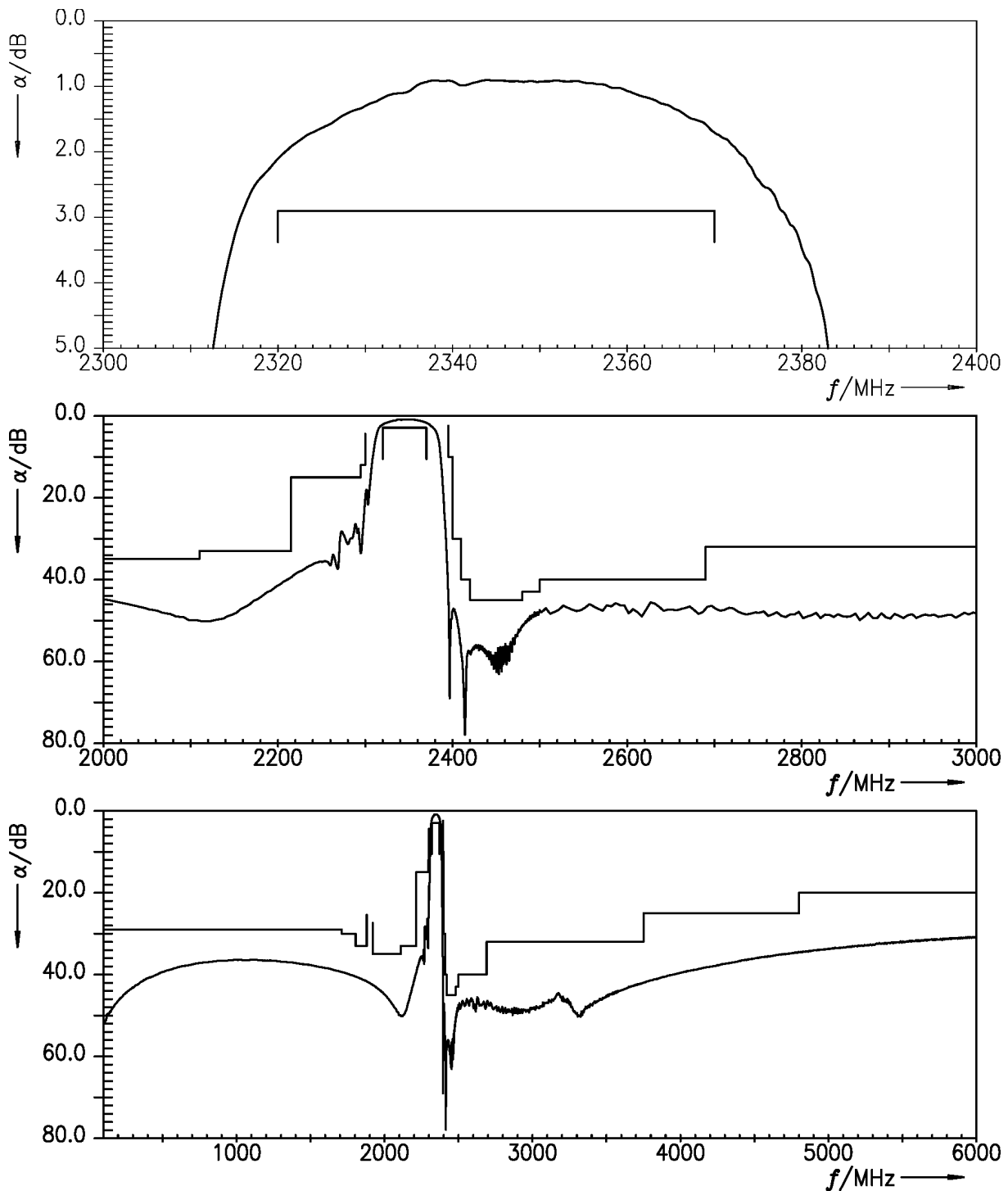


Figure 4: Attenuation .

9 Reflection coefficients

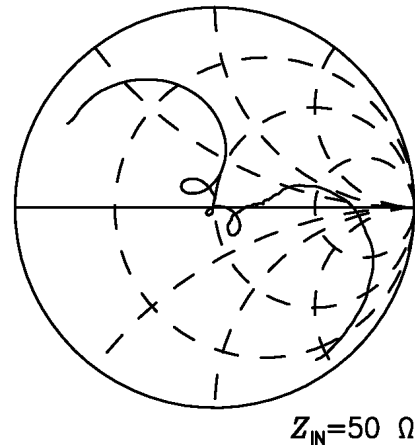
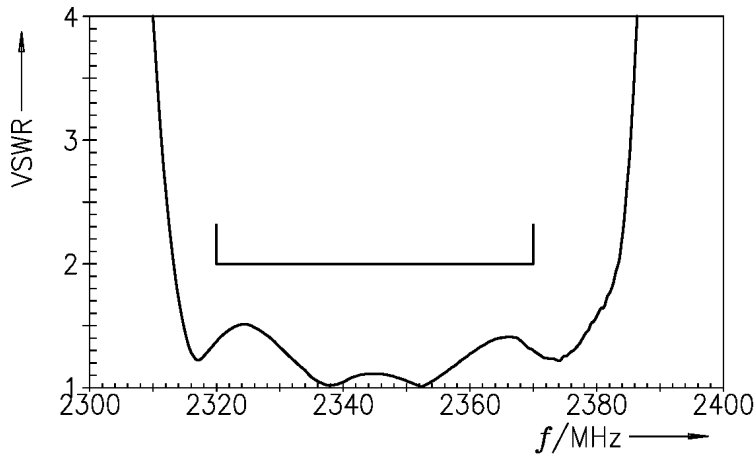


Figure 5: Reflection coefficient at input port.

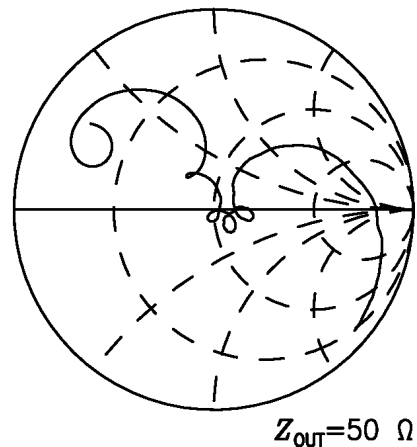
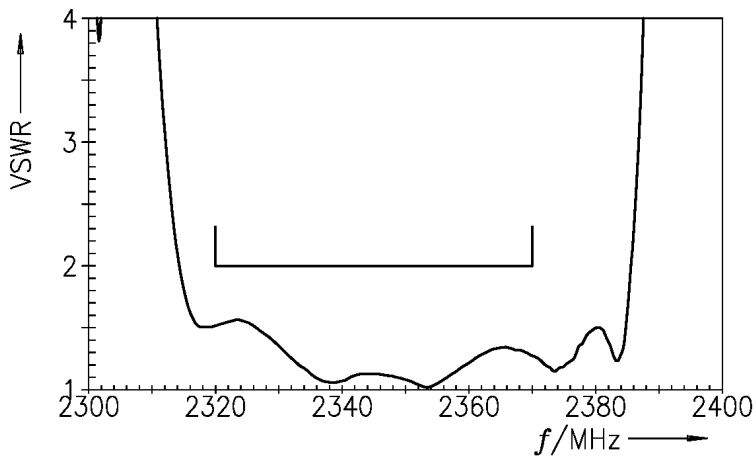


Figure 6: Reflection coefficient at output port.

## 10 EVM

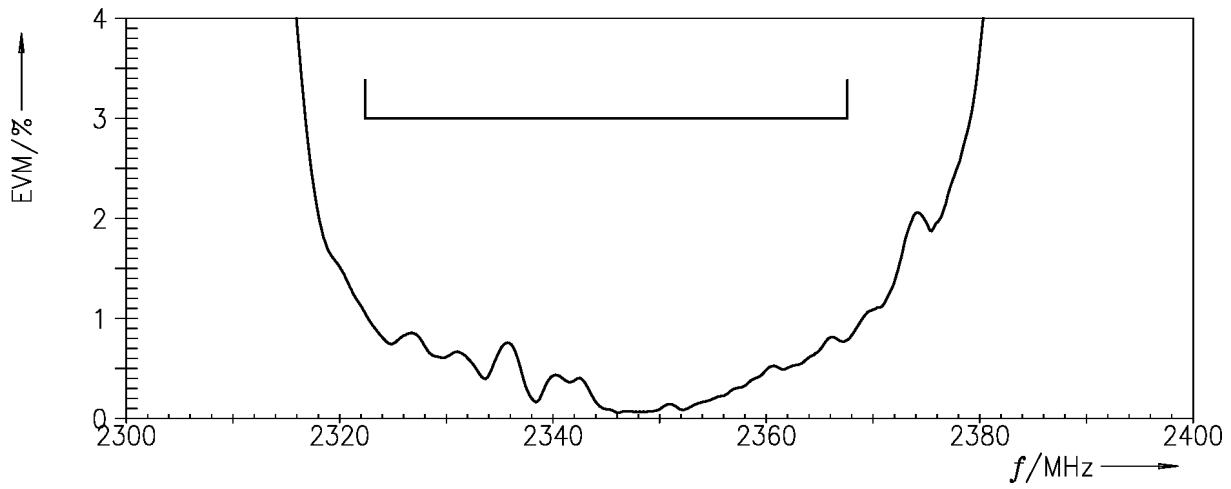
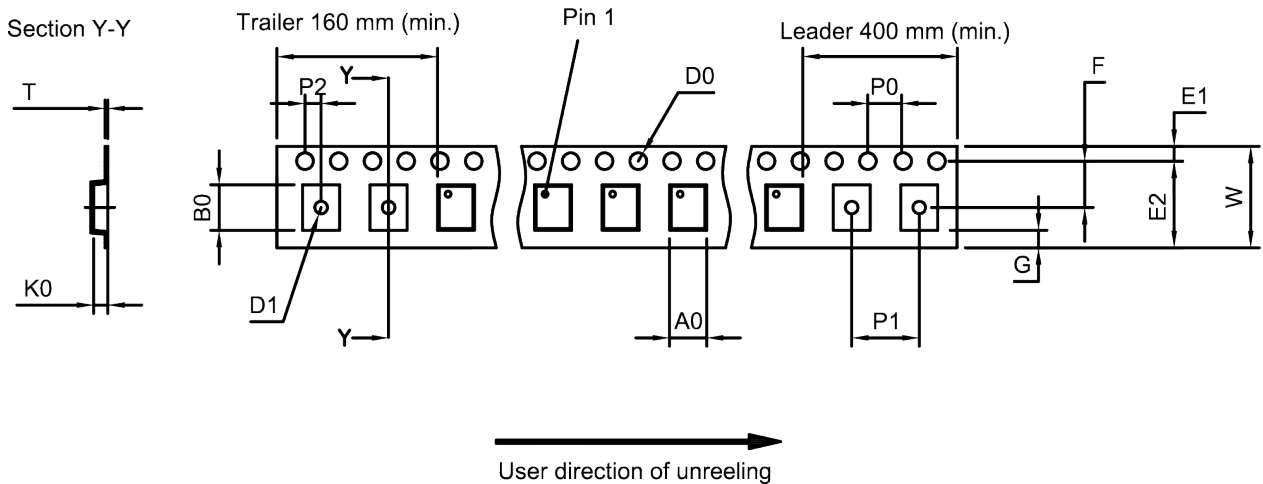


Figure 7: Error vector magnitude .



11 Packing material

11.1 Tape



**Figure 8:** Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A <sub>0</sub>	1.27±0.05 mm
B <sub>0</sub>	1.57±0.05 mm
D <sub>0</sub>	1.5+0.1/-0 mm
D <sub>1</sub>	0.5±0.1 mm
E <sub>1</sub>	1.75±0.1 mm

E <sub>2</sub>	6.25 mm (min.)
F	3.5±0.05 mm
G	0.75 mm (min.)
K <sub>0</sub>	0.62±0.05 mm
P <sub>0</sub>	4.0±0.1 mm

P <sub>1</sub>	4.0±0.1 mm
P <sub>2</sub>	2.0±0.05 mm
T	0.25±0.03 mm
W	8.0+0.3/-0.1 mm

**Table 1:** Tape dimensions.

11.2 Reel with diameter of 180 mm

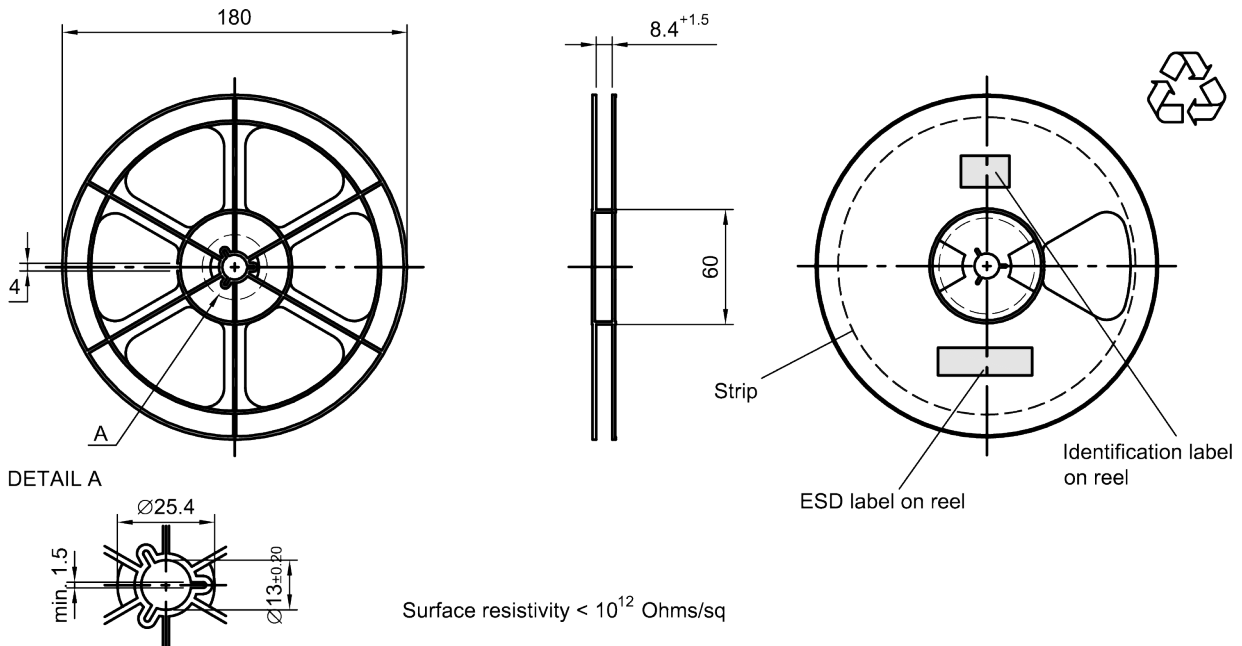


Figure 9: Drawing of reel (first-angle projection) with diameter of 180 mm.

Dimensions [mm]

X = 220+5

Y = 235+5

Sealing area 10±3

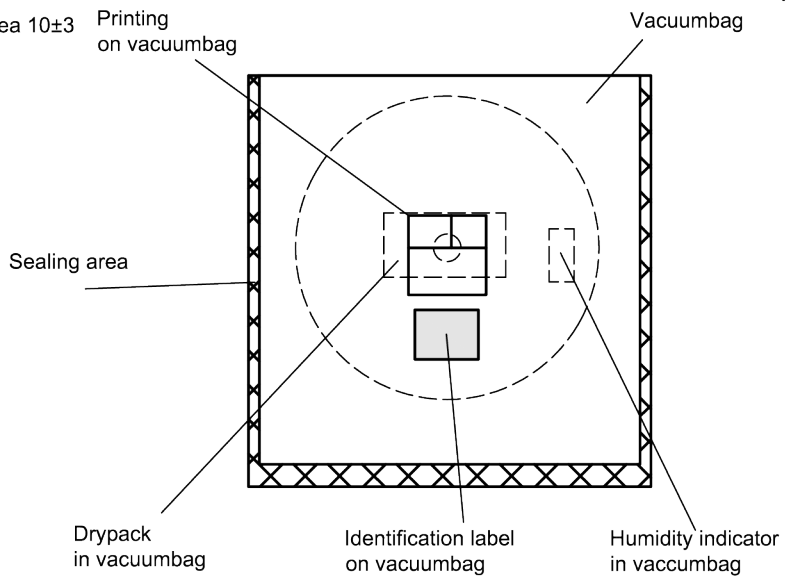
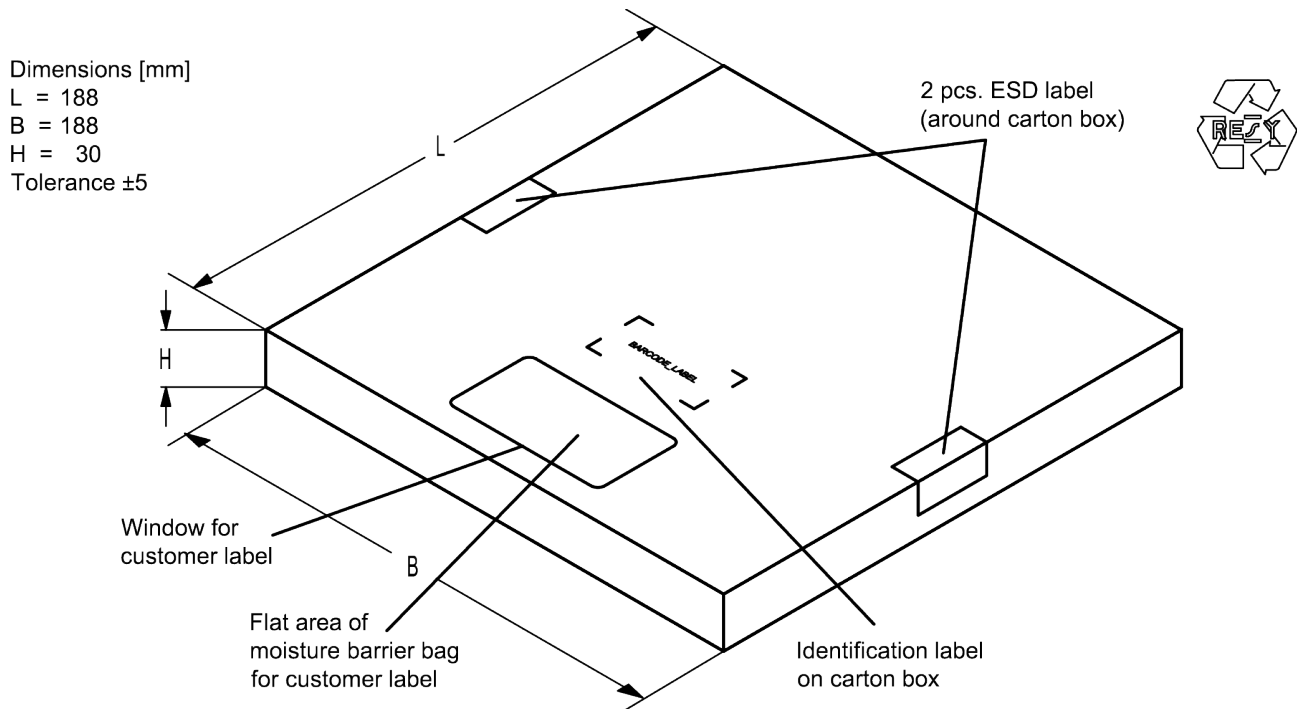


Figure 10: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



**Figure 11:** Drawing of folding box for reel with diameter of 180 mm.

**12 Marking**

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:

The 4 digit type number of the ordering code, e.g., B3xxxxB**1234**xxxx,  
is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.  
**16J** => **1234**  
 $1 \times 32^2 + 6 \times 32^1 + 18 (=J) \times 32^0 =$  **1234**  
 The BASE32 code for product type B9637 is 9D5.

■ Lot number:

The last 5 digits of the lot number, e.g., **12345**,  
are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.  
**5UY** => **12345**  
 $5 \times 47^2 + 27 (=U) \times 47^1 + 31 (=Y) \times 47^0 =$  **12345**

Adopted BASE32 code for type number			
Decimal value	Base32 code	Decimal value	Base32 code
0	0	16	G
1	1	17	H
2	2	18	J
3	3	19	K
4	4	20	M
5	5	21	N
6	6	22	P
7	7	23	Q
8	8	24	R
9	9	25	S
10	A	26	T
11	B	27	V
12	C	28	W
13	D	29	X
14	E	30	Y
15	F	31	Z

Adopted BASE47 code for lot number			
Decimal value	Base47 code	Decimal value	Base47 code
0	0	24	R
1	1	25	S
2	2	26	T
3	3	27	U
4	4	28	V
5	5	29	W
6	6	30	X
7	7	31	Y
8	8	32	Z
9	9	33	b
10	A	34	d
11	B	35	f
12	C	36	h
13	D	37	n
14	E	38	r
15	F	39	t
16	G	40	v
17	H	41	\
18	J	42	?
19	K	43	{
20	L	44	}
21	M	45	<
22	N	46	>
23	P		

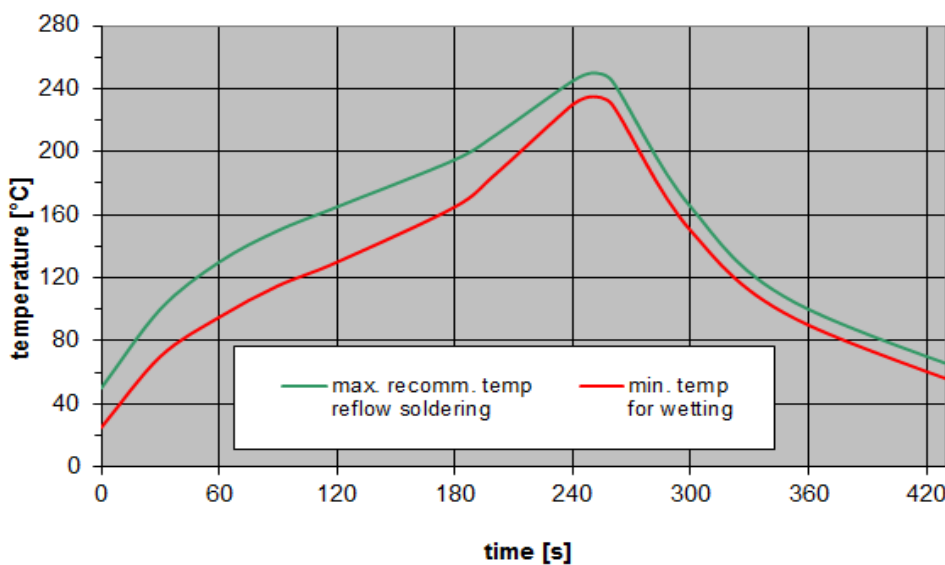
**Table 2:** Lists for encoding and decoding of marking.

### 13 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3<sup>rd</sup> edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature $T_{peak}$	250 °C +0/-5 °C
wetting temperature $T_{min}$	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

**Table 3:** Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).



**Figure 12:** Recommended reflow profile for convection and infrared soldering – lead-free solder.

## 14 Annotations

### 14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

### 14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

### 14.3 Ordering codes and packing units

Ordering code	Packing unit
B39232B9637P810	5000 pcs

**Table 4:** Ordering codes and packing units.

## 15 Cautions and warnings

### 15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under [www.rf360jv.com/orderingcodes](http://www.rf360jv.com/orderingcodes).

### 15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

### 15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

### 15.4 Package information

#### Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

#### Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Dimensions do not include burrs.

#### Projection method

Unless otherwise specified first-angle projection is applied.

## 16 Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, RF360 Europe GmbH and its affiliates are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an RF360 product with the properties described in the product specification is suitable for use in a particular customer application.
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